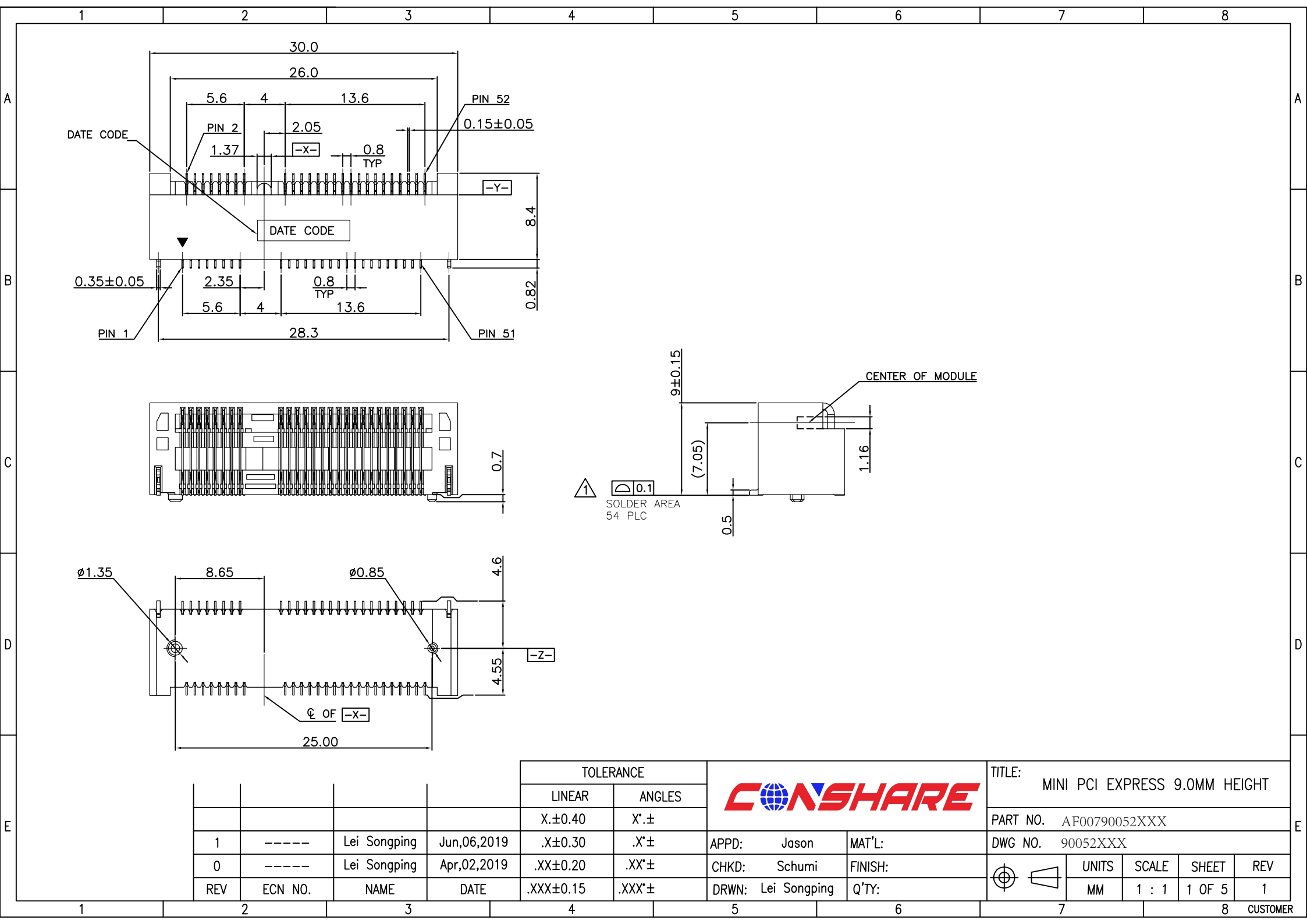




NOTES:

1. MATERIAL:

HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-0, BLACK COLOR,
CONTACTS: COPPER ALLOY.
PEGS: COPPER ALLOY.

2. FINISH:

CONTACTS: SELECTED GOLD PLATING ON THE CONTACT AREA,
1u" MIN. GOLD PLATING ON THE SOLDER TAILS,
50 u" MIN. NICKEL UNDERPLATING OVER ALL.
PEGS: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

3. PACKAGING SPECIFICATION: 9130404001

4. PRODUCT SPECIFICATION: PS-MINI PCI-E-01

5. DATE CODE.

YYWWDD

YY: YEAR (19: 2019)

WW: WEEK (25: THE 25TH WEEK)

DD: (D1~D7: SUNDAY~SATURDAY)

PRODUCT NUMBER CODE

AF007 90 052 R X XX

90: 9.0H HEIGHT

52 CONTACTS

PACKING OPTIONS
R: TAPE & REEL

HALOGEN OPTIONS
NONE: HALOGEN
HF: HALOGEN FREE

CONTACT AREA PLATING
0: 30u" GOLD
1: 10u" GOLD
2: GOLD FLASH

				TOLERANCE				TITLE: MINI PCI EXPRESS 9.0MM HEIGHT					
				LINEAR	ANGLES								
				X.±0.40	X'.±								
				X.±0.40	X'.±			PART NO. AF00790052XXX					
1	-----	Lei Songping	Jun,06,2019	.X±0.30	.X'±	APPD:	Jason	MAT'L:	DWG NO. 90052XXX				
0	-----	Lei Songping	Apr,02,2019	.XX±0.20	.XX'±	CHKD:	Schumi	FINISH:		UNITS	SCALE	SHEET	REV
REV	ECN NO.	NAME	DATE	.XXX±0.15	.XXX'±	DRWN:	Lei Songping	Q'TY:		MM	1 : 1	2 OF 5	1

1

2

3

4

5

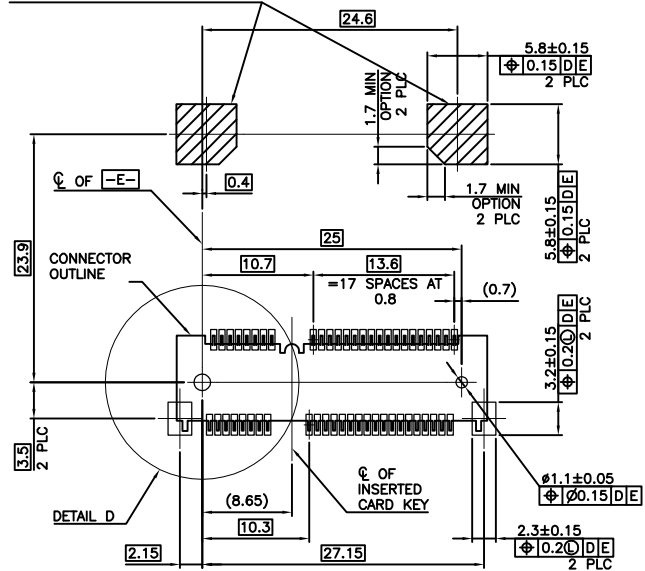
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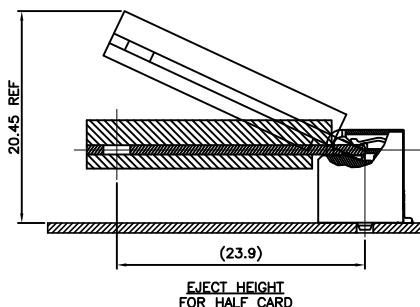
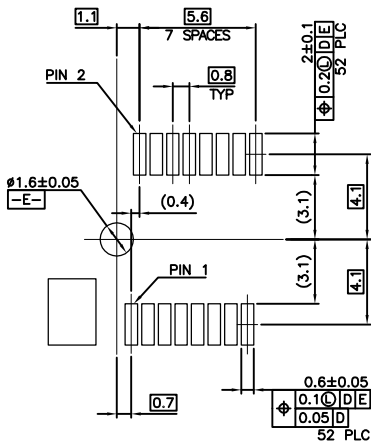
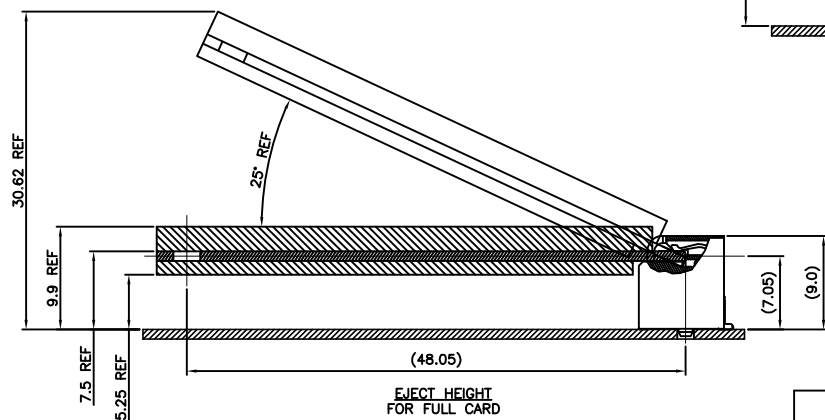
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CUSTOMER

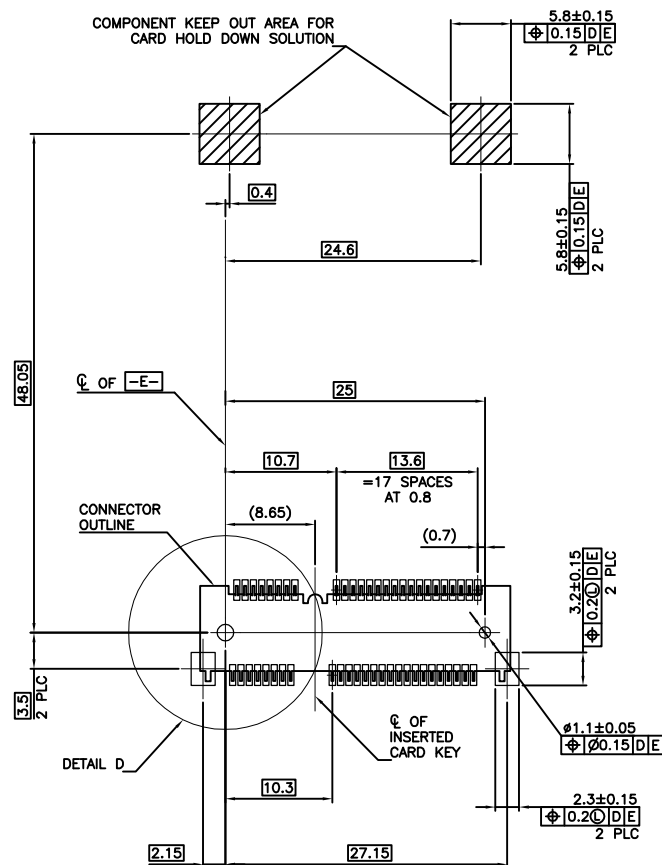
COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



—D— IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



—D— IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR FULL CARD CONNECTOR
(TOP VIEW)

REV	ECN NO.	NAME	DATE
1	-----	Lei Songping	Jun,06,2019
0	-----	Lei Songping	Apr,02,2019

TOLERANCE	
LINEAR	ANGLES
X.±	X°.±
.X±	.X°.±
.XX±	.XX°.±
.XXX±	.XXX°.±



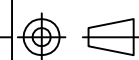
APPD: Jason
CHKD: Schumi
DRWN: Lei Songping

MAT'L:
FINISH:
Q'TY:

TITLE: MINI PCI EXPRESS 9.0MM HEIGHT

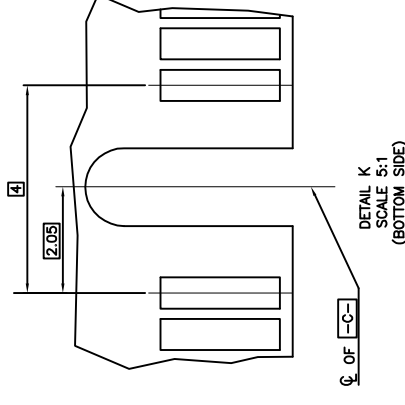
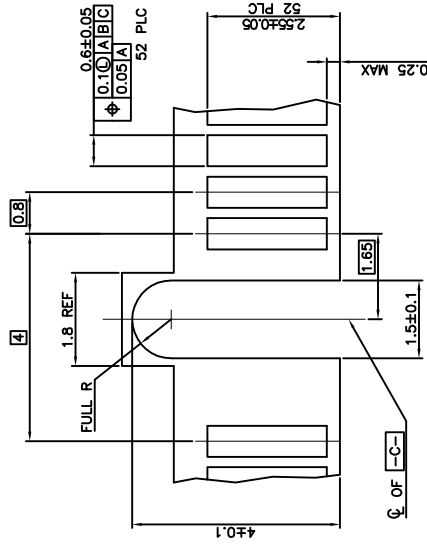
PART NO. AF00790052XXX

DWG NO. 90052XXX



UNITS	SCALE	SHEET	REV
MM	1 : 1	3 OF 5	1

8 CUSTOMER



NOTES:

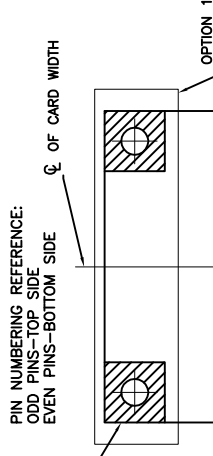
△ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.

△ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS

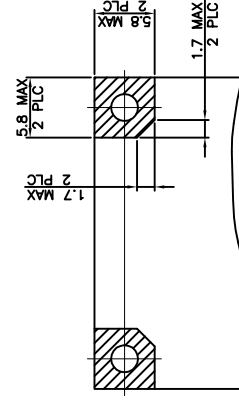
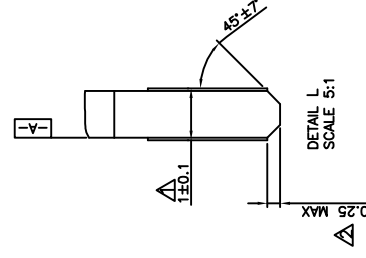
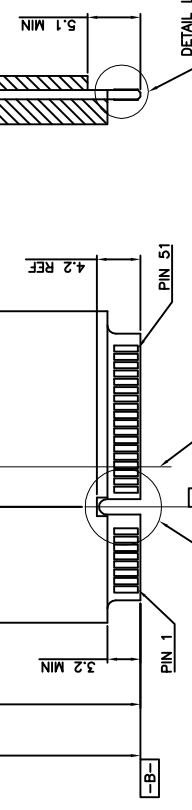
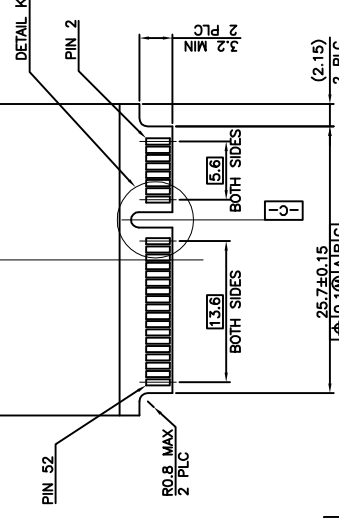
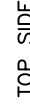


COMPONENT AND ROUTING (ALL LAYERS)
KEEP OUT AREA FOR HOLD DOWN SOLUTIONS

**PIN NUMBERING REFERENCE:
ODD PINS—TOP SIDE**



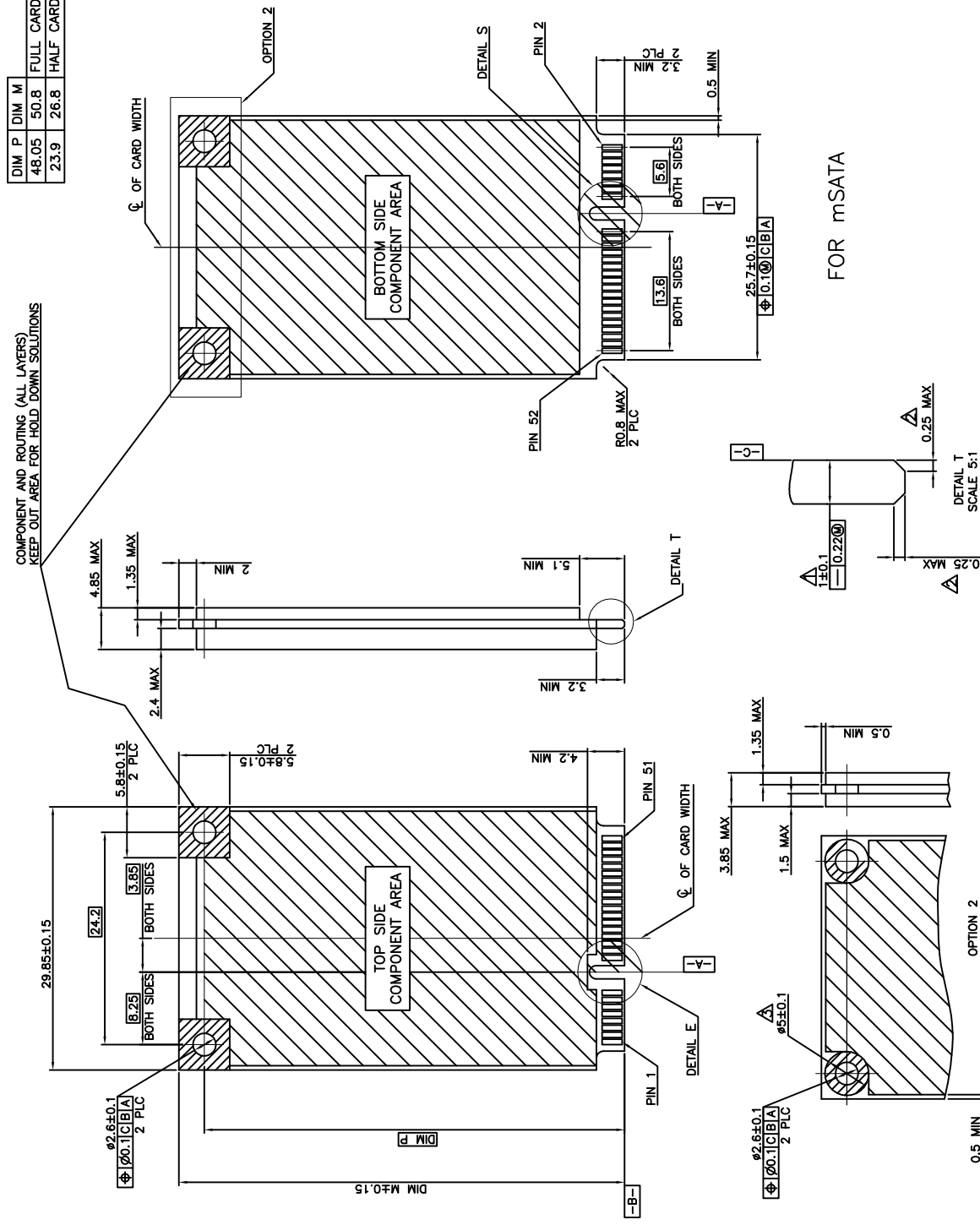
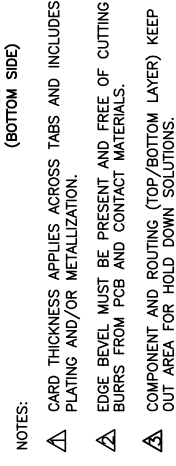
HATCHED AREAS ILLUSTRATE
MAXIMUM AVAILABLE
COMPONENT VOLUME



OPTION 1
FOR HALF-MINI CARD
(TOP & BOTTOM SIDE)

FOR PCI EXPRESS MINI CARD

[illegible]



FOR mSATA

DIM P	DIM M	
48.05	50.8	FULL CARD
23.9	26.8	HALF CARD

TITLE: MINI PCI EXPRESS 9.0MM HEIGHT				
PART NO. AF00790052XXX				
DWG NO. 90052XXX				
	UNITS	SCALE	SHEET	REV
	MM	1 : 1	5 OF 5	1
7			8 CUSTOMER	